

### TO-247-2L 650V SiC Schottky Diode EL-SAB00865JA



$V_{RRM}$	=	650	V
$Q_C$	=	12	nC
$I_F$	=	8	A
$V_F$	=	1.5	V

#### Features

- Low Forward Voltage ( $V_F$ )
- Shorter recovery time
- High speed switching
- High surge current capability
- Enabling higher frequency and increased power density
- System efficiency improvement
- System cost and size savings due to the reduced cooling requirements
- Pb-Free, Halogen Free, RoHS Compliant



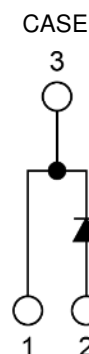
#### Benefits

- Improve System Efficiency
- Reduction of Heat Sink Requirement
- Essentially No Switching Losses
- Parallel Devices Without Thermal Runaway

#### Applications

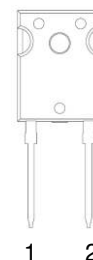
- Power Factor Correction in SMPS
- Solar inverter
- Uninterruptible Power Supply
- Motor Drives
- Data Center

#### Schematic



#### Pin Configuration

1. Cathode
  2. Anode
- CASE: Cathode



#### Key Performance Parameters

Symbol	$V_{RRM}$	$I_F$	$I_{FSM}$	$Q_C$	$T_{J,max}$
Value	650V	8A	29A	12nC	175°C
Condition	$T_C@25^{\circ}C$		$t_p=10ms$ $T_C@25^{\circ}C$ Sine half wave	$V_R=400V, T_j=25^{\circ}C$ $Q_C = \int_0^{V_R} C(V)dV$	-

Maximum Ratings

Parameter	Symbol	Value	Unit	Test condition
Repetitive Peak Reverse Voltage	$V_{RRM}$	650	V	
Surge Peak Reverse Voltage	$V_{RSM}$	650	V	
DC Blocking Voltage	$V_R$	650	V	
Continuous Forward Current	$I_F^{*1}$	8	A	
Surge non-repetitive forward current	$I_{FSM}$	29	A	$T_C= 25^{\circ}C$ , $t_p= 10ms$ Sine half wave
Total power dissipation	$P_D^{*1}$	42	W	$T_C= 25^{\circ}C$
Junction temperature	$T_J$	175	$^{\circ}C$	
Storage temperature	$T_{STG}$	-55 / +175	$^{\circ}C$	
Mounting Torque	$M_d$	1 8.8	Nm lbf-in	M3 or 6-32 screw

\*1 Limited by maximum  $T_A$  and for Max.  $R_{thJC}$ .

Thermal Characteristics (Measured conformable to JESD51-14.)

Parameter	Symbol	Value		Unit
		Typ	Max	
Thermal Resistance from Junction to Case	$R_{th(JC)}$	1.9	-	$^{\circ}C/W$

Electrical Characteristics

Parameter	Symbol	Values			Unit	Test condition
		Min.	Typ.	Max.		
DC blocking voltage	V <sub>DC</sub>	650	-	-	V	T <sub>J</sub> = 25°C, I <sub>R</sub> = 100μA
Forward voltage	V <sub>F</sub>	-	1.5	1.85	V	I <sub>F</sub> = 8A, T <sub>J</sub> = 25°C
			1.85	-		I <sub>F</sub> = 8A, T <sub>J</sub> = 175°C
Reverse current	I <sub>R</sub>	-	2	40	μA	V <sub>R</sub> = 520V, T <sub>J</sub> = 25°C
			20	-		V <sub>R</sub> = 520V, T <sub>J</sub> = 175°C
Total capacitance	C	-	208	-	pF	V <sub>R</sub> = 1V, f= 1MHz,
			23			V <sub>R</sub> = 200V, f= 1MHz
			18			V <sub>R</sub> = 400V, f= 1MHz
Capacitance Stored Energy	E <sub>C</sub>	-	1.7		μJ	V <sub>R</sub> = 400V
Total capacitive charge	Q <sub>C</sub>	-	12	-	nC	V <sub>R</sub> = 400V, T <sub>J</sub> = 25°C $Q_C=\int_0^{V_R} C(V)dV$

# Typical Performance

V<sub>F</sub>-I<sub>F</sub> Characteristics

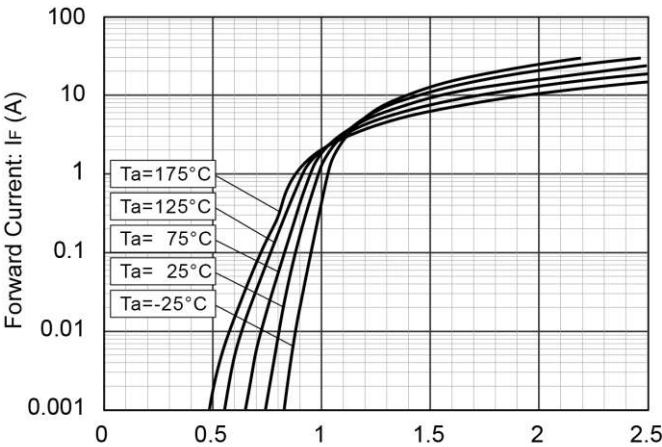


Figure1. Forward Voltage: V<sub>F</sub> (V)

V<sub>F</sub>-I<sub>F</sub> Characteristics

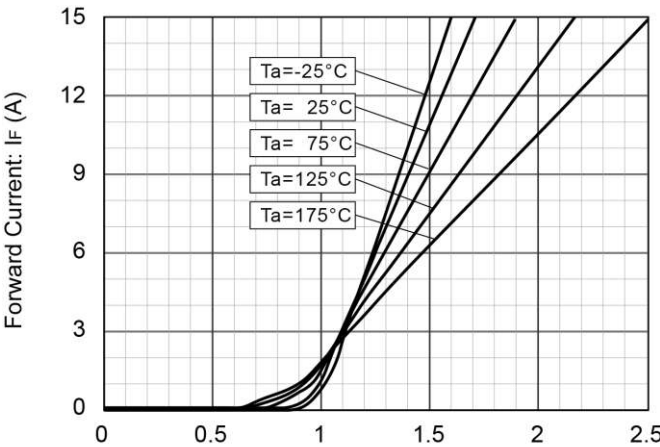


Figure2. Forward Voltage: V<sub>F</sub> (V)

V<sub>R</sub>-I<sub>R</sub> Characteristics

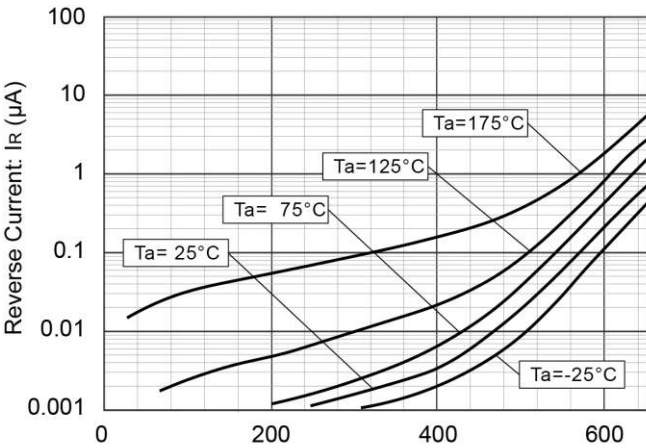


Figure3. Reverse Voltage: V<sub>R</sub> (V)

V<sub>R</sub>-C<sub>t</sub> Characteristics

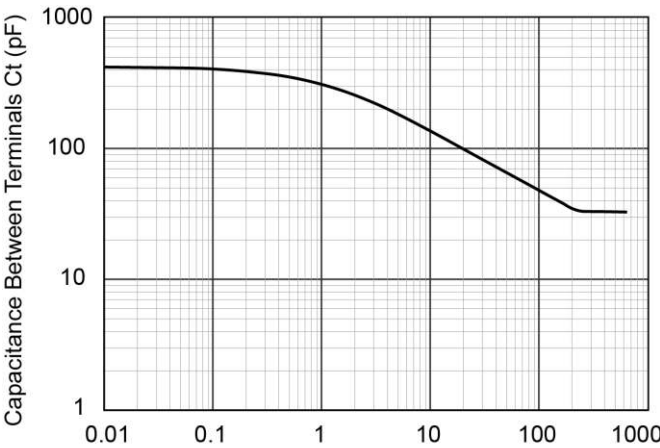


Figure4. Reverse Voltage: V<sub>R</sub>(V) Ta = 25 °C f = 1MHz

Maximum I<sub>p</sub> – T<sub>c</sub> Characteristics

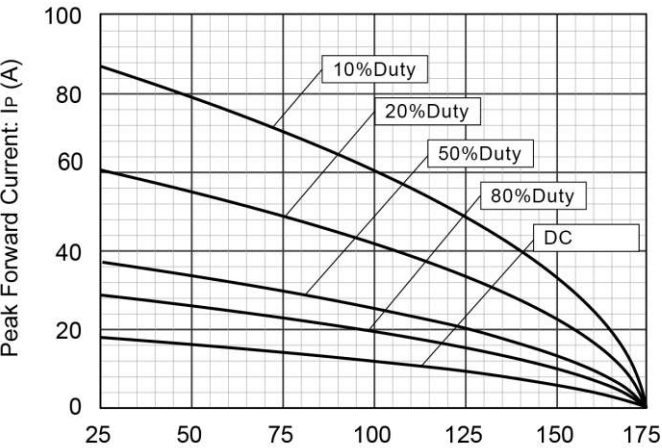


Figure5. Case Temperature: T<sub>c</sub> (°C)

Power Dissipation

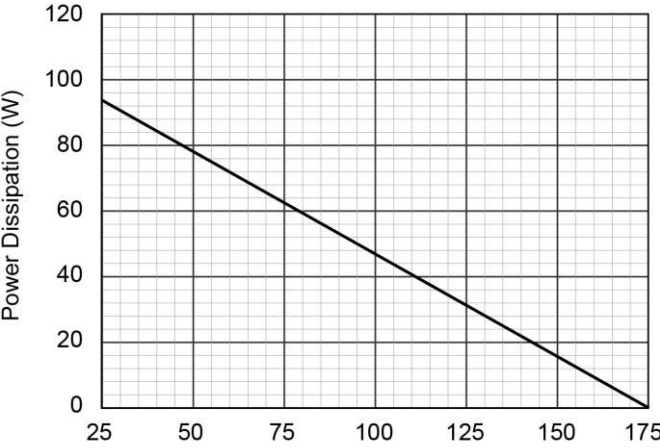


Figure6. Case Temperature: T<sub>c</sub> (°C)

## $I_{FSM} - P_W$ Characteristics

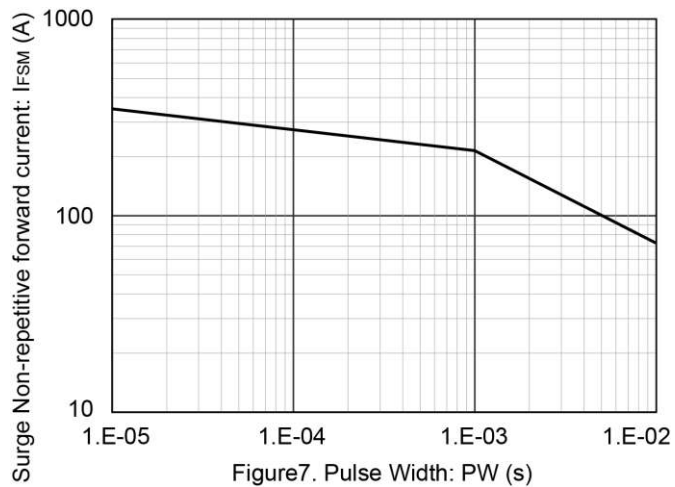


Figure7. Pulse Width:  $PW$  (s)

## $E_C - V_R$ Characteristics

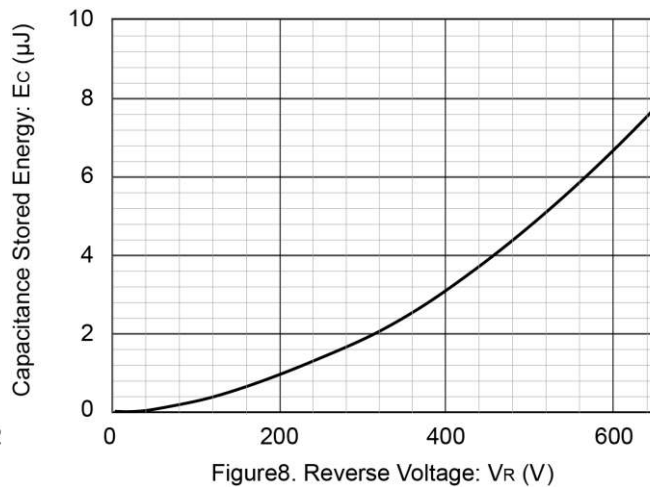


Figure8. Reverse Voltage:  $V_R$  (V)

## Typical Transient Thermal Resistance vs. Pulse Width

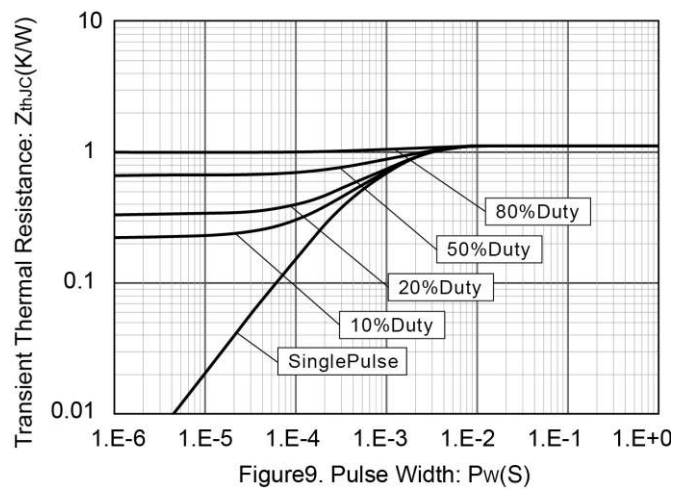
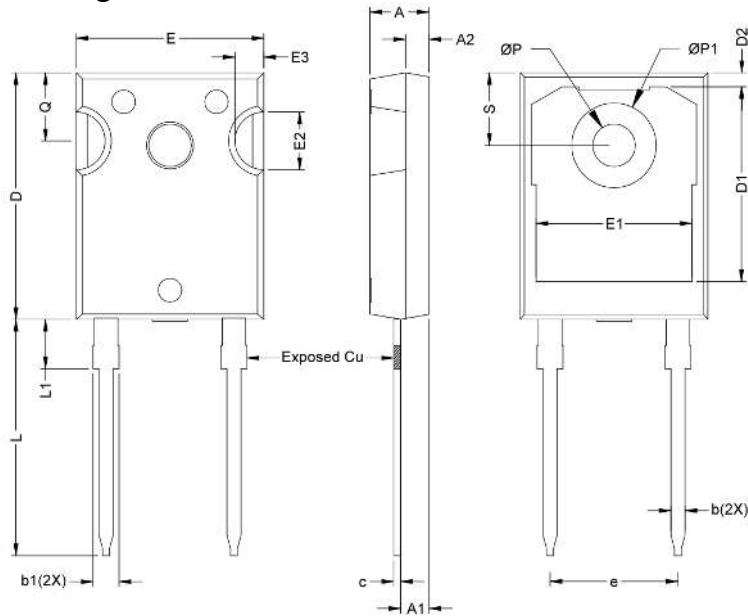


Figure9. Pulse Width:  $Pw$  (S)

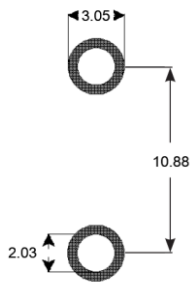
# Package Outlines



DIM	MILIMETERS		
	MIN	TYP.	MAX
A	4.82	5.02	5.22
A1	2.21	2.41	2.61
A2	1.8	2	2.2
b	0.95	1.2	1.45
b1	1.95	2.2	2.45
c	0.35	0.6	0.85
D	20.75	20.95	21.15
D1	16.3	16.55	16.8
D2	0.99	1.19	1.39
E	15.74	15.94	16.14
E1	13.01	13.26	13.51
E2	4.71	4.91	5.11
E3	2.26	2.46	2.66
e	10.88BSC.		
L	19.82	20.07	20.32
L1	3.94	4.19	4.44
P	3.41	3.61	3.81
P1	6.94	7.19	7.44
Q	5.59	5.79	5.99
S	5.97	6.17	6.37

Unit : mm

# Recommended pad layout for surface mount leadform



Unit : mm

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